

特征 Features

- 齐纳击穿阻抗低; Low Zener Impedance
- 最大功率耗散 300mW; Power Dissipation of 300mW
- 高稳定性和可靠性。High Stability and High Reliability

机械数据 Mechanical Data

- 封装: SOT-23 封装 SOT-23 Small Outline Plastic Package
- 环氧树脂 UL 易燃等级 Epoxy UL: 94V-0
- 安装位置: 任意 Mounting Position: Any

极限值和温度特性(TA = 25°C 除非另有规定)

Maximum Ratings & Thermal Characteristics (Ratings at 25°C ambient temperature unless otherwise specified.)

参数 Parameters	符号 Symbol	数值 Value	单位 Unit
功率消耗 Power Dissipation	Pd	500 ¹⁾	mW
正向压降 Forward Voltage @IF=10mA	Vf	0.9 ²⁾	V
热阻 Thermal Resistance, Junction-to-Ambient	RθJA	417 ³⁾	°C/W
热阻 Thermal Resistance, Junction-to-Lead	RθJL	150 ³⁾	°C/W
存储温度 Storage temperature range	Ts	-65-+150	°C

1) Device mounted on ceramic PCB: 7.6mm x 9.4mm x 0.87mm with pad areas 25mm²

2) Short duration test pulse used to minimize self-heating effect

3) Thermal Resistance measurement obtained via infrared Scan Method.

4) f=1KHz

电特性 (TA = 25°C 除非另有规定)

Electrical Characteristics (Ratings at 25°C ambient temperature unless otherwise specified.)

型号	印字 (代码)	Vz1(@Izt)			Zzt@Izt	Zzk		IR	
		Min (V)	Max (V)	Izt mA	Max Ω	Max Ω	Izk mA	Max uA	VR V
MMBZ5221C	2KC1	2.35	2.45	20	30	1200	0.25	100	1.0
MMBZ5222C	2KC2	2.45	2.55	20	30	1250	0.25	100	1.0
MMBZ5223C	2KC3	2.65	2.75	20	30	1300	0.25	75	1.0
MMBZ5225C	2KC5	2.94	3.06	20	30	1600	0.25	50	1.0
MMBZ5226C	2KG1	3.23	3.37	20	28	1600	0.25	25	1.0
MMBZ5227C	2KG2	3.53	3.67	20	24	1700	0.25	15	1.0
MMBZ5228C	2KG3	3.82	3.98	20	23	1900	0.25	10	1.0
MMBZ5229C	2KG4	4.21	4.39	20	22	2000	0.25	5.0	1.0
MMBZ5230C	2KG5	4.61	4.79	20	19	1900	0.25	5.0	2.0
MMBZ5231C	2KE1	5.00	5.20	20	17	1600	0.25	5.0	2.0
MMBZ5232C	2KE2	5.49	5.71	20	11	1600	0.25	5.0	3.0
MMBZ5233C	2KE3	5.88	6.12	20	7	1600	0.25	5.0	3.5
MMBZ5234C	2KE4	6.08	6.32	20	7	1000	0.25	5.0	4.0
MMBZ5235C	2KE5	6.66	6.94	20	5	750	0.25	3	5.0
MMBZ5236C	2KF1	7.35	7.65	20	6	500	0.25	3	6.0
MMBZ5237C	2KF2	8.04	8.36	20	8	500	0.25	3	6.5
MMBZ5238C	2KF3	8.53	8.87	20	8	600	0.25	3	6.5

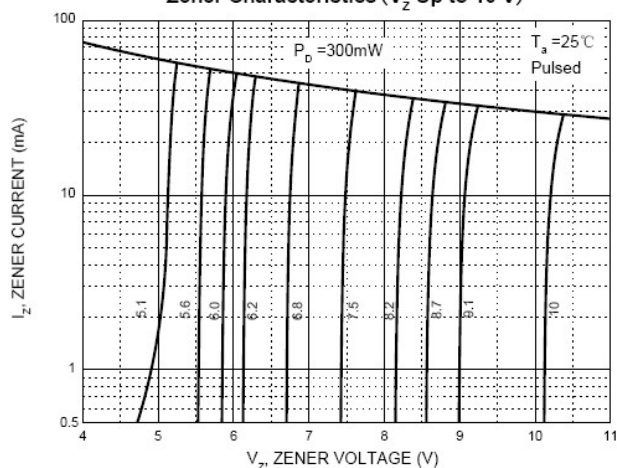
MMBZ5221C- MMBZ 5259C Series

型号	印字 (代码)	Vz1(@Izt)			Zzt@Izt	Zzk		IR	
		Min	Max	Izt	Max	Max	Izk	Max	VR
		(V)	(V)	mA	Ω	Ω	mA	μ A	V
MMBZ5239C	2KF4	8.92	9.28	20	10	600	0.25	3	7.0
MMBZ5240C	2KF5	9.80	10.20	20	17	600	0.25	3	8.0
MMBZ5241C	2KH1	10.78	11.22	20	22	600	0.25	2.0	8.4
MMBZ5242C	2KH2	11.72	12.24	20	30	600	0.25	1.0	9.1
MMBZ5243C	2KH3	12.74	13.26	9.5	13	600	0.25	0.5	9.9
MMBZ5244C	2KH4	13.72	14.28	9.0	15	600	0.25	0.1	10
MMBZ5245C	2KH5	14.70	15.30	8.5	16	600	0.25	0.1	11
MMBZ5246C	2KJ1	15.68	16.32	7.8	17	600	0.25	0.1	12
MMBZ5247C	2KJ2	16.66	17.34	7.5	19	600	0.25	0.1	13
MMBZ5248C	2KJ3	17.64	18.36	7.0	21	600	0.25	0.1	14
MMBZ5249C	2KJ4	18.62	19.38	6.6	23	600	0.25	0.1	14
MMBZ5250C	2KJ5	19.60	20.40	6.2	25	600	0.25	0.1	15
MMBZ5251C	2KK1	21.56	22.44	5.6	29	600	0.25	0.1	17
MMBZ5252C	2KK2	23.52	24.48	5.2	33	600	0.25	0.1	18
MMBZ5253C	2KK3	24.50	25.50	5.0	35	600	0.25	0.1	19
MMBZ5254C	2KK4	26.46	27.54	5.0	41	600	0.25	0.1	21
MMBZ5255C	2KK5	27.44	28.56	4.5	44	600	0.25	0.1	21
MMBZ5256C	2KM1	29.40	30.60	4.2	49	600	0.25	0.1	23
MMBZ5257C	2KM2	32.34	33.66	3.8	58	700	0.25	0.1	25
MMBZ5258C	2KM3	35.28	36.72	3.4	70	700	0.25	0.1	27
MMBZ5259C	2KM4	38.22	39.78	3.2	80	800	0.25	0.1	30

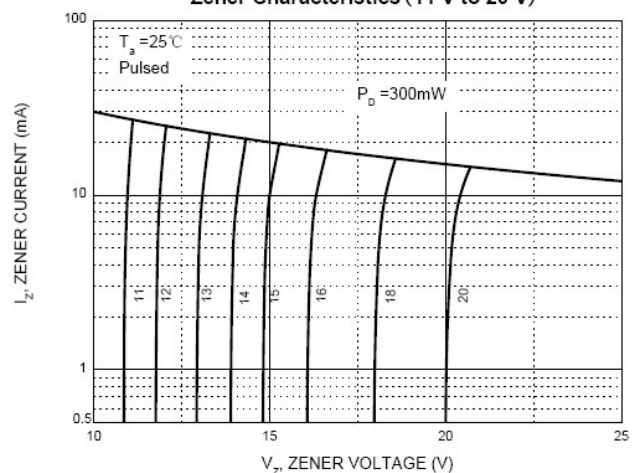
Typical Characteristics

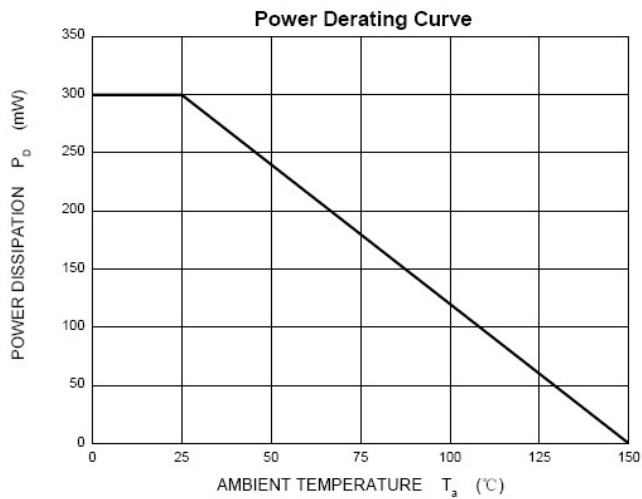
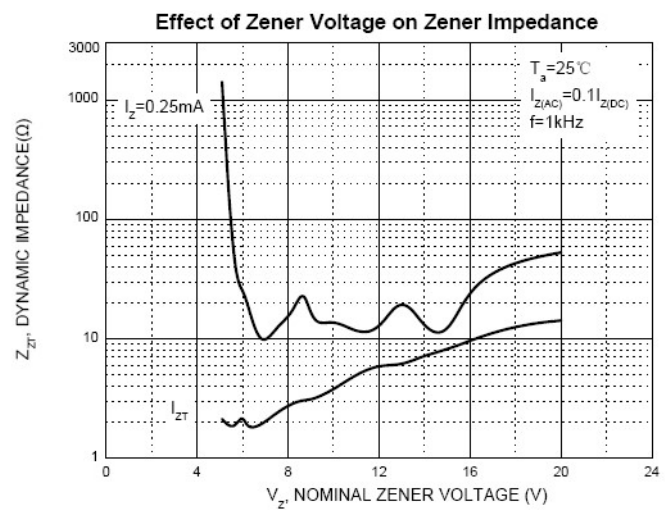
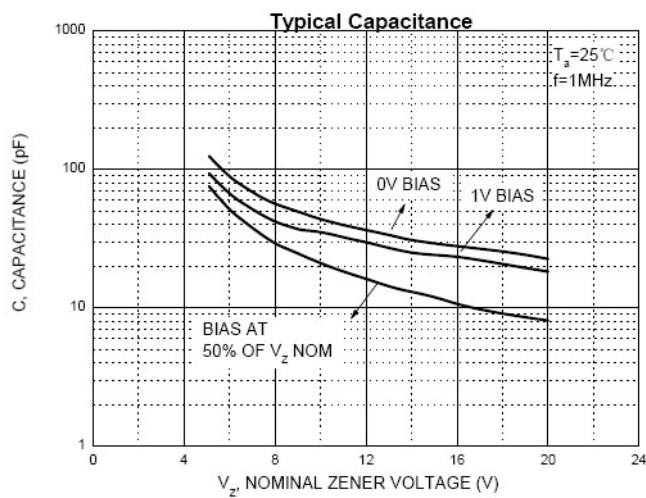
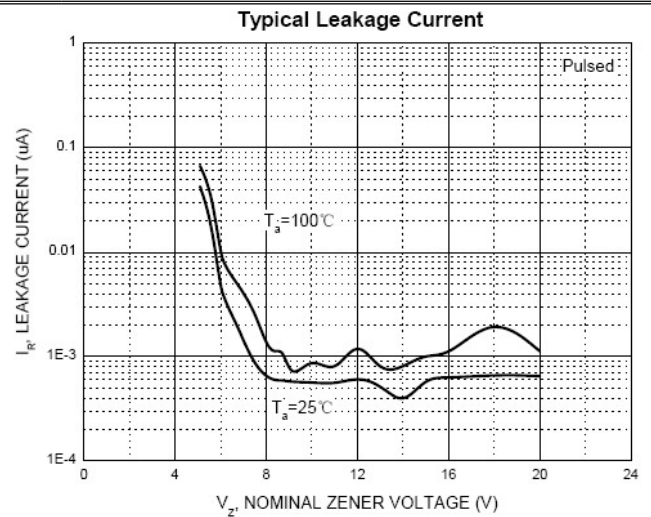
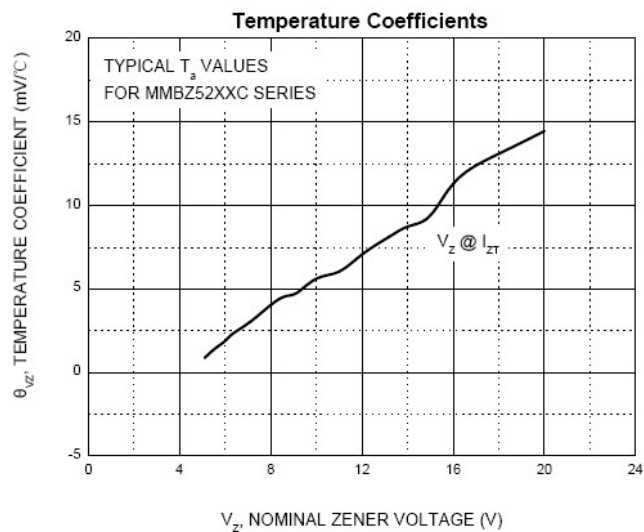
Notes: Our company currently provide 5.1 V - 20 V products only

Zener Characteristics (V_z Up to 10 V)

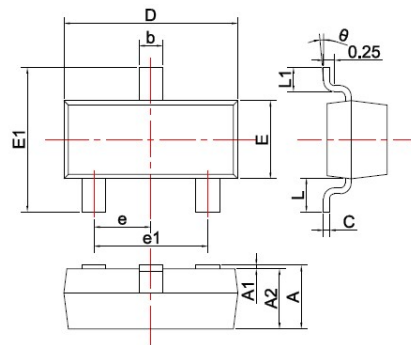


Zener Characteristics (11 V to 20 V)





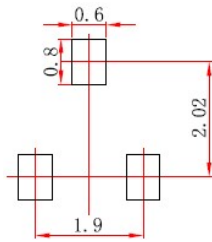
SOT-23 PACKAGE OUTLINE Plastic surface mounted package



SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.500
θ	0°	8°

Unit: mm

焊盘设计参考Precautions: PCB Design(Recommended land dimensions for SOT-23 diode. Electrode patterns for PCBs)



- Note:
- 1.Controlling dimension;in millimeters.
 - 2.General tolerance:± 0.05mm.
 - 3.The pad layout is for reference purposes only.